



**부산대학교**  
PUSAN NATIONAL UNIVERSITY



# Advanced Manufacturing & Optical Instrumentation Lab.

## 첨단생산 및 광계측 실험실

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Pusan National University  
School of Mechanical Engineering  
Prof. Yangjin Kim

# Principal Investigator

## Prof. Yangjin Kim, PhD



### Education



- **The University of Tokyo** 04/2012 – 03/2015  
PhD in Mechanical Engineering
- **The University of Tokyo** 04/2007 – 03/2009  
MS in Mechanical Engineering
- **The University of Tokyo** 04/2003 – 03/2007  
BS in Mechanical Engineering

### Experience



- **Pusan National University** 09/2020 – Current  
Associate Professor, School of Mechanical Engineering
- **The University of Tokyo** 03/2024 – 02/2025  
Associate Professor, Department of Mechanical Engineering
- **Pusan National University** 09/2016 – 08/2020  
Assistant Professor, School of Mechanical Engineering
- **The University of Tokyo** 02/2016 – 08/2016  
Assistant Professor, Department of Mechanical Engineering
- **The University of Tokyo** 04/2015 – 01/2016  
Postdoctoral Researcher, Department of Mechanical Engineering
- **Korea Institute of Machinery and Materials** 02/2009 – 03/2012  
Technical Research Personnel (Military Service)

## Precision Measurement

### Phase extraction from fringe patterns

- Traditional phase shifting
- Iterative method
- Machine learning (deep learning)

### Measurement of optical devices

- Surface topography
- Thickness (absolute, variation)
- Refractive index (reflectivity)
- Simultaneous measurement
- Absolute radius

## Machine Tool

### FEA modeling of machine tool

- Modeling of machine tool joints
- Stiffness tuning of machine tool joints
- Volumetric error compensation

### Structural/thermal analysis

- Rib structure of bed and column
- Spindle of steel composites
- Turning center turret of CFRP
- Applications of new materials to frame of machine tools

# Conference

## Domestic conference



## International conference





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# Precision Measurement using Optical Interferometry



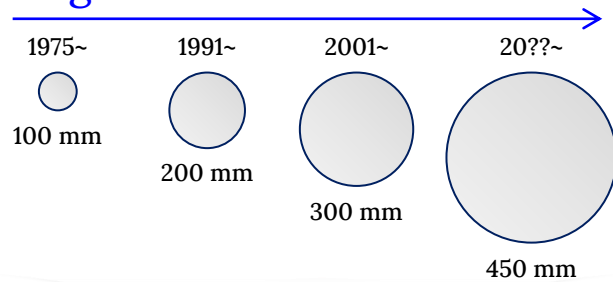
**SAMSUNG**

# Semiconductor Lithography Equipment

## Semiconductor industry

- 1 Low cost
- 2 Mass Production
- 3 Miniaturized circuit of chip

### Large diameter of wafer



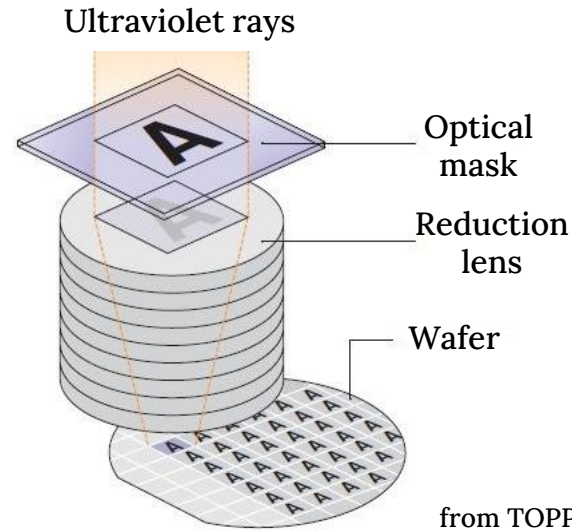
### Large diameter of blank mask

### Wavelength

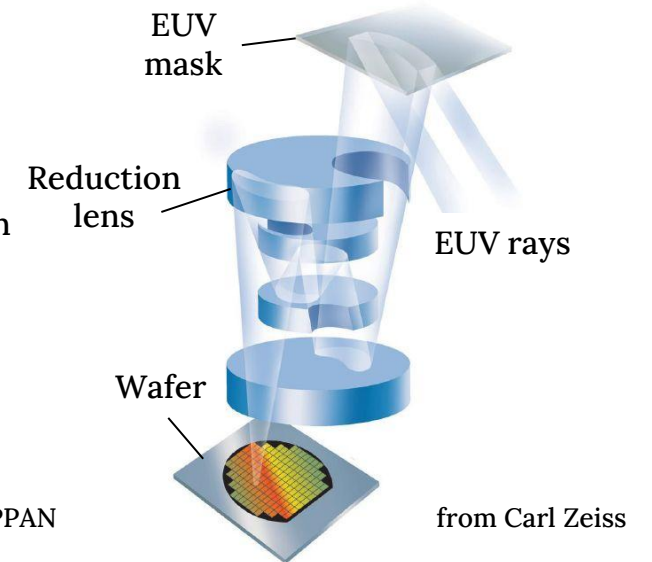
Optical Mask (transmission)  
 i-Line(365 nm)  
 KrF(248 nm)  
 ArF(193 nm)

EUV Mask (reflection)  
 EUV (13.5 nm)

## Optical lithography



## EUV lithography



	2023	2024	2025	2026	2027
Optical mask substrate flatness [nm]	37	33	29	26	24
EUV mask substrate flatness [nm]	11	10	9	8	7
EUV mask substrate flatness metrology uncertainty [nm 3σ]	2.2	2.0	1.9	1.8	1.7

from 2020 IRDS

Precise measurement of **transparent plate and lens**  
 (surface shape, thickness, refractive index...)

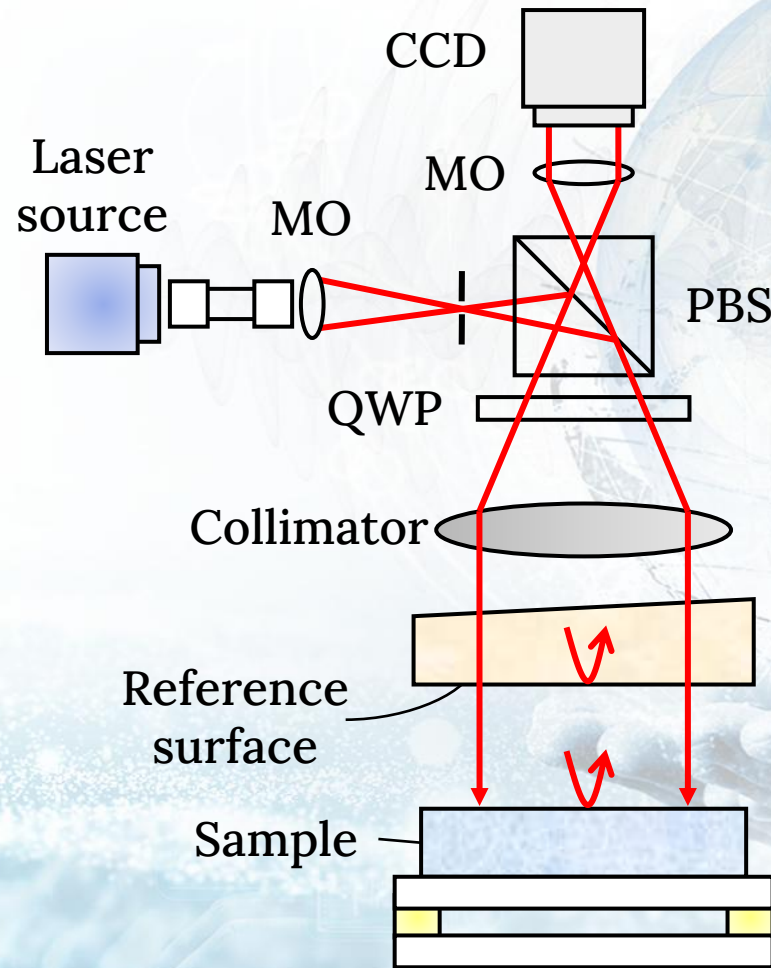
# Ideal Measurement System

- High accuracy (excellent measurement uncertainty)
- Low cost (large-aperture measurement)
- Non-contact testing
- Simultaneous measurement (thickness & surface shape...)
- Complex surface

## Wavelength tuning Fizeau interferometry

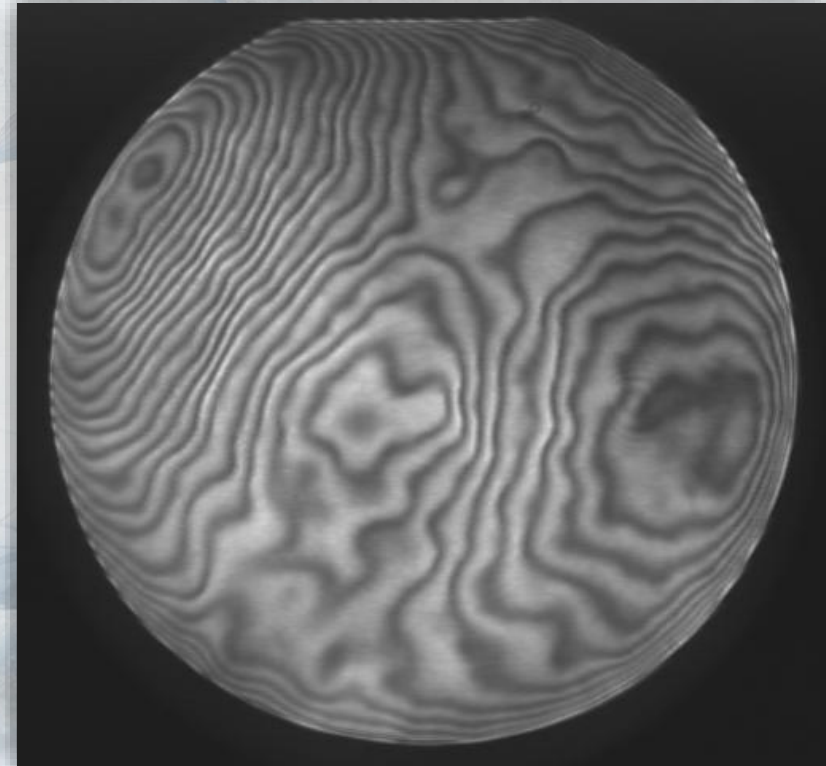
- Fizeau interferometer
- Phase extraction from the observed interferograms

# Fizeau Interferometer



- MO: microscope objective
- PBS: polarized beam splitter
- QWP: quarter-wave plate

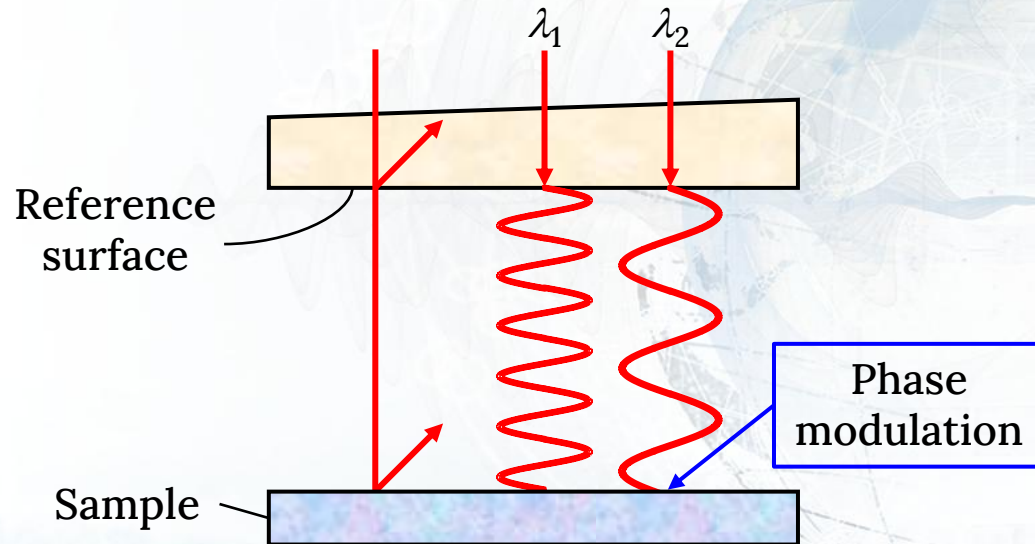
- Interferogram (sample: silicon wafer)



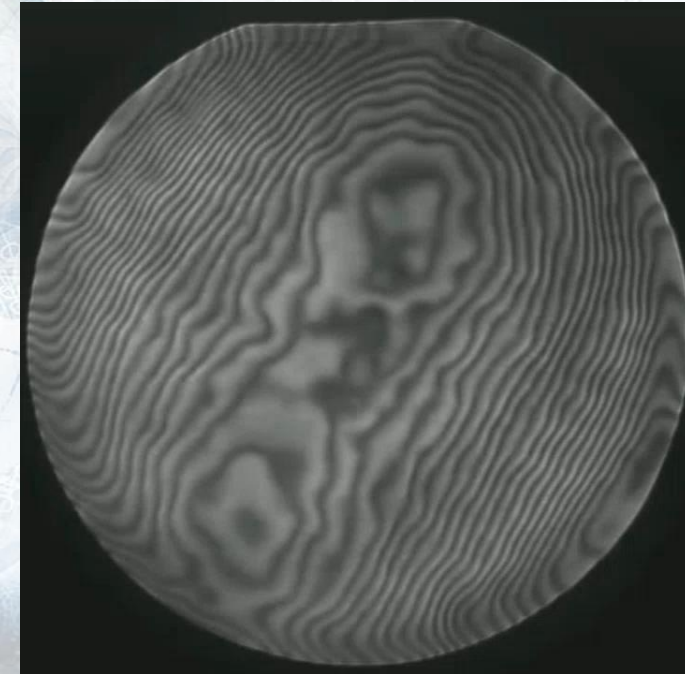
- Less susceptible to air disturbance
- Easy to extend to the measurement of large-aperture sample

# Wavelength Tuning Interferometry

- Wavelength tuning from  $\lambda_1$  to  $\lambda_2$  ( $\lambda_1 < \lambda_2$ )



- Interferogram



- Intensity during wavelength tuning

$$I(\alpha_r) = I_0 + I_1 \cos(\alpha_r - \varphi)$$

$I(\alpha_r)$ : intensity of the  $r$ th image

$I_0$ : intensity of DC component

$I_1$ : intensity of fundamental signal

$r$ : sampling number

$\alpha_r$ : phase-shift parameter

$\varphi$ : target phase (phase of surface shape)

- Image acquisitions during wavelength tuning
- Calculation of phase  $\varphi$

- ✓ Surface shape
- ✓ Optical thickness variation

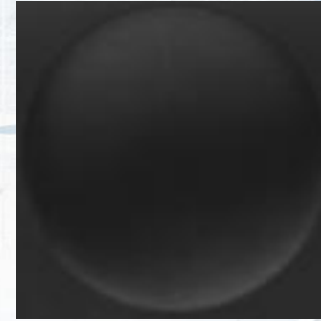
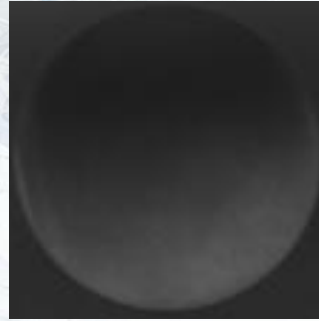
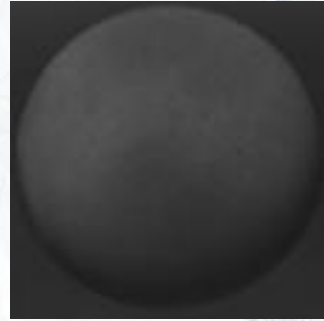
# Phase Extraction from Interferograms

$$I(\alpha_r) = I_0 [1 + \gamma \cos(\alpha_r + \varphi)]$$

3 variables



Minimum 3 interferograms



Phase Extraction  $\varphi$  (calculation)

## Phase-shifting technique

- Fringe patterns (~ 50)
- Environmental uncertainties
- Commercialized (ZYGO)

## Iterative method

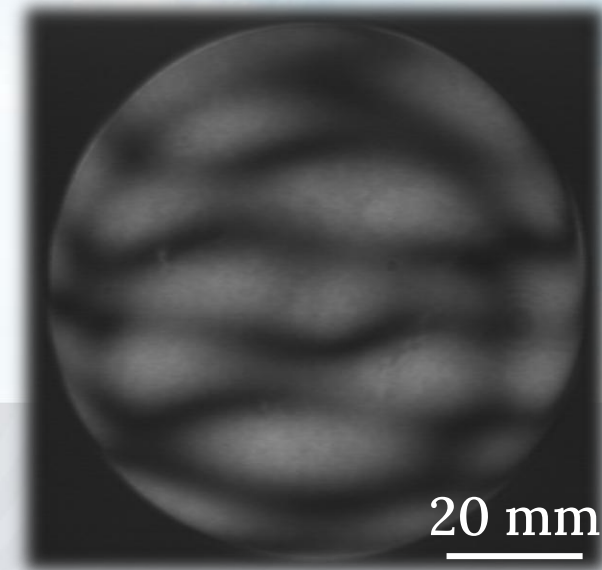
- Fringe patterns (~ 10)
- Error from singular matrix
- Not commercialized

## Machine learning

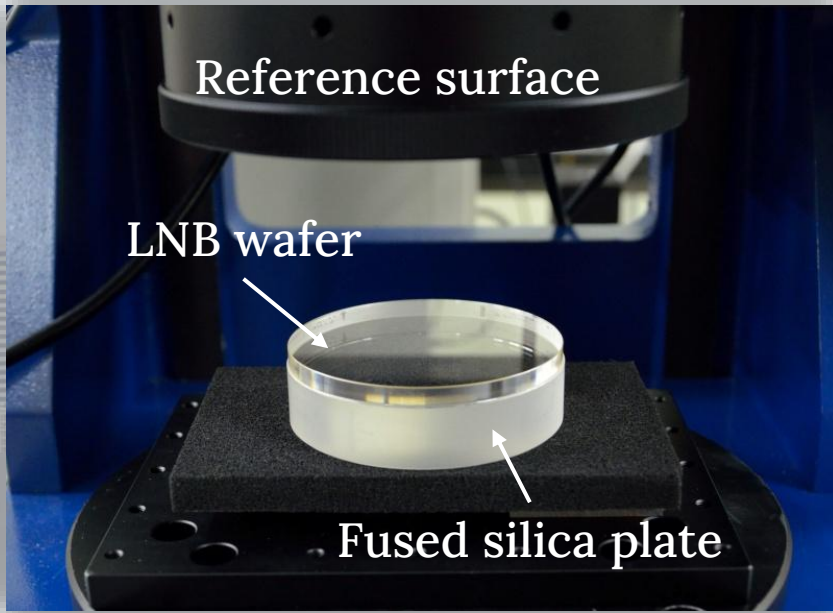
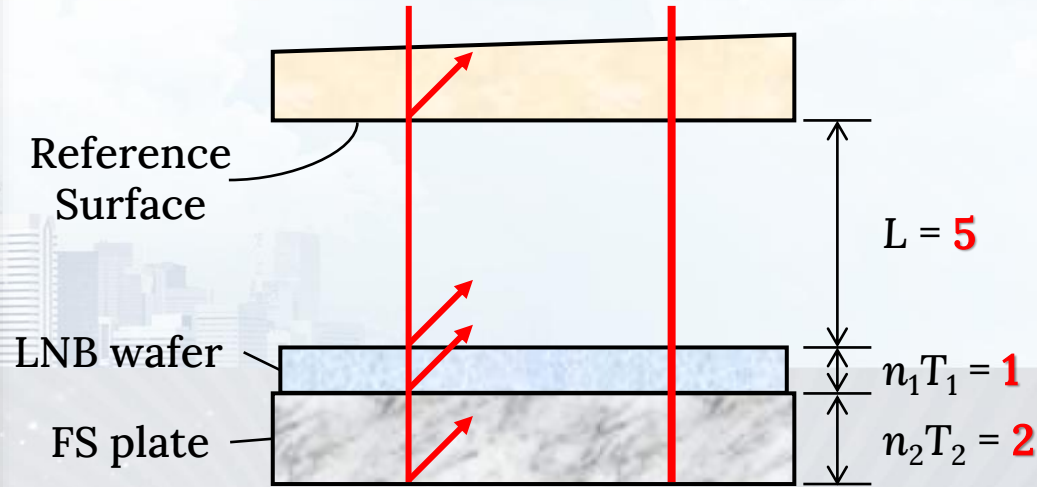
- Fringe patterns (only 2)
- Great accuracy
- Not commercialized

# Application 1 : Multi-Layer Interferometry

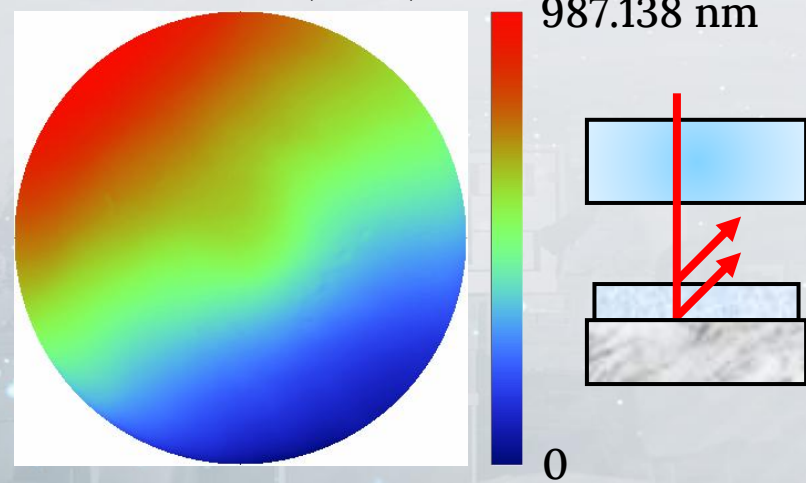
Raw interferogram



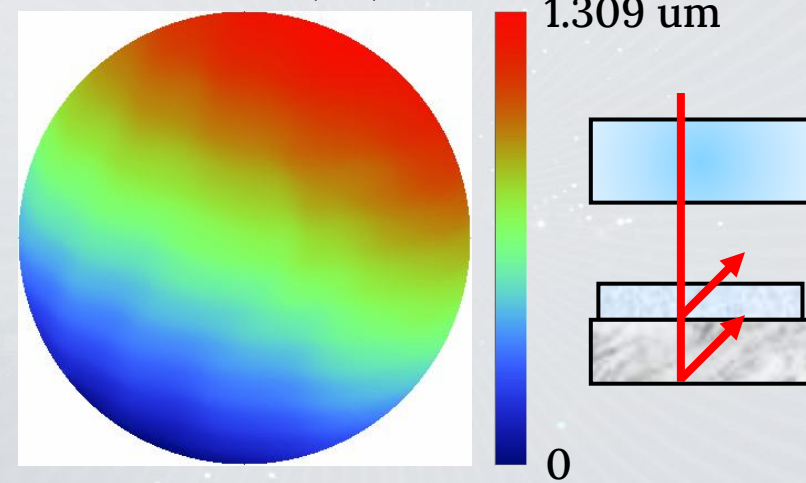
- 6 different fringe patterns ( ${}_4C_2 = 6$ )



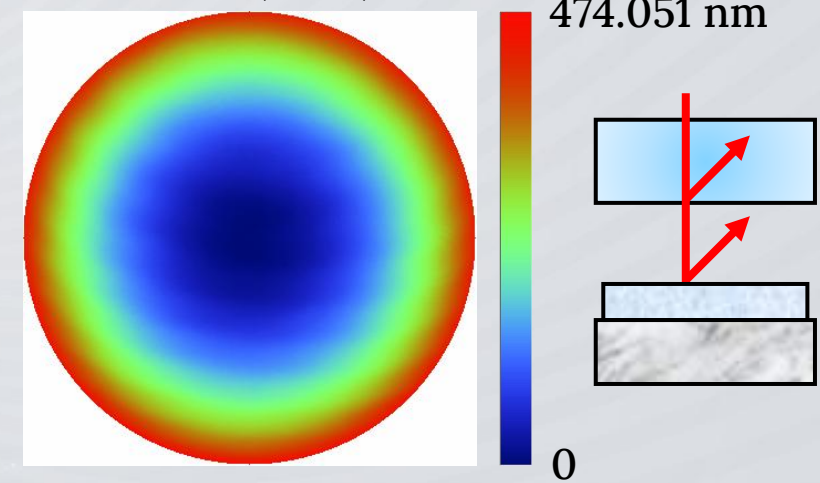
- Thickness (LNB)



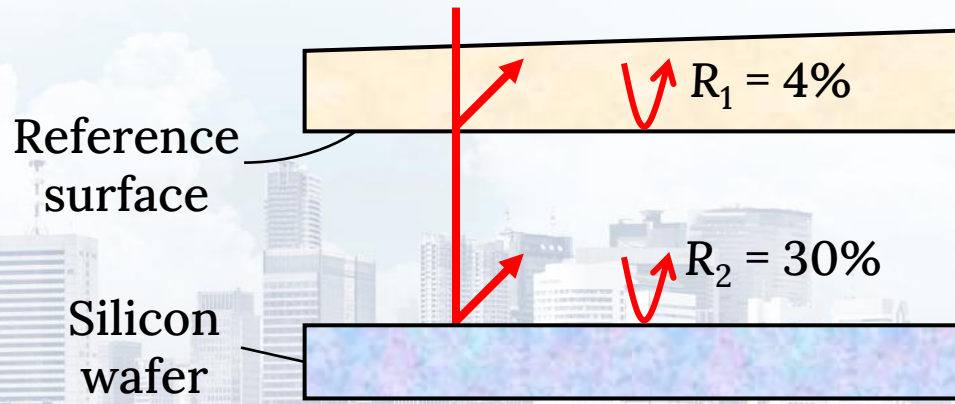
- Thickness (FS)



- Surface (LNB)

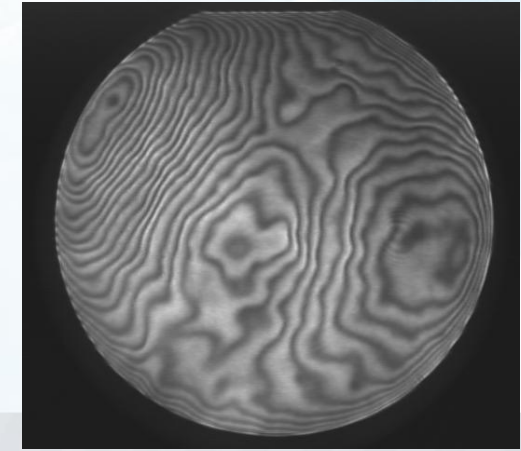


# Application 2 : Surface Topography of Wafer



Reflectivity: 30%

Raw interferogram



## Intensity of fringe pattern

$$I(\alpha_r) = I_0 + \underbrace{I_0\gamma_1 \cos(\varphi_1 - \alpha_r)}_{\text{Fundamental signal}} + \underbrace{I_0\gamma_2 \cos(\varphi_2 - 2\alpha_r)}_{\text{2nd harmonic signal}} + \underbrace{I_0\gamma_3 \cos(\varphi_3 - 3\alpha_r)}_{\text{3rd harmonic signal}} \dots$$

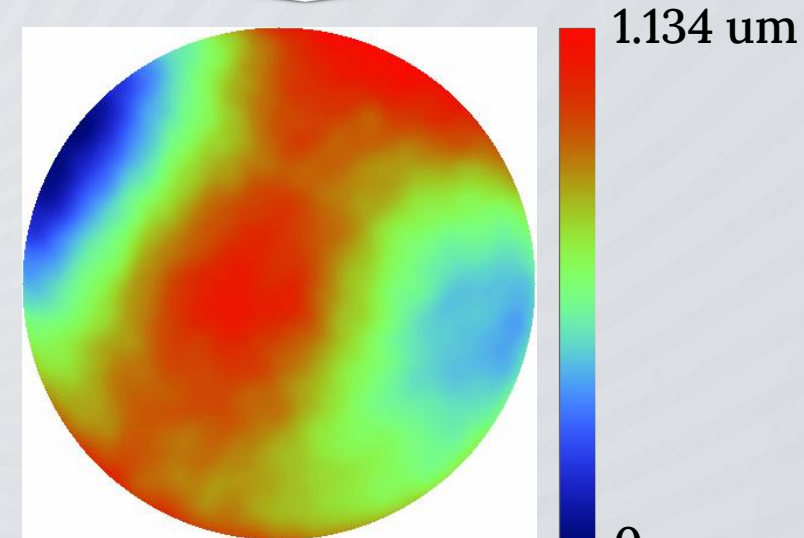
Fundamental signal

2<sup>nd</sup> harmonic signal

3<sup>rd</sup> harmonic signal

**Coupling error** between harmonics and phase-shift error

4N - 3 phase-shifting algorithm



Measurement accuracy: 2.2 nm

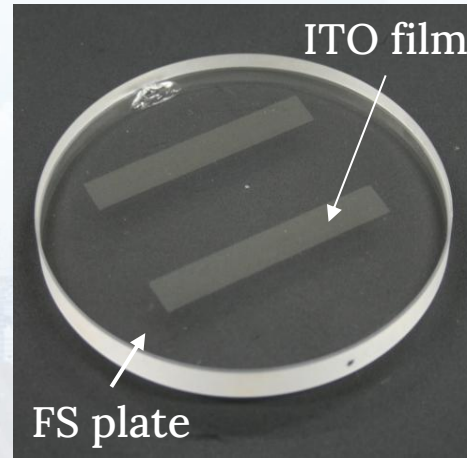
# Application 3 : Thickness Profiling of ITO Film

- Indium Tin Oxide thin film (ITO film)

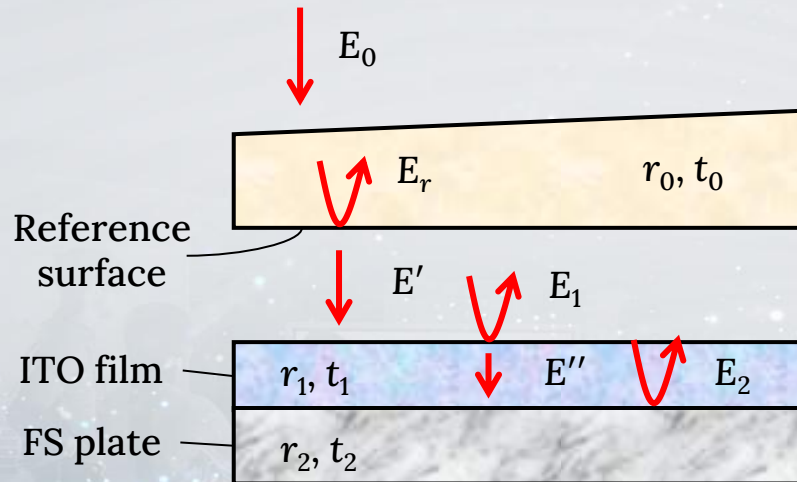
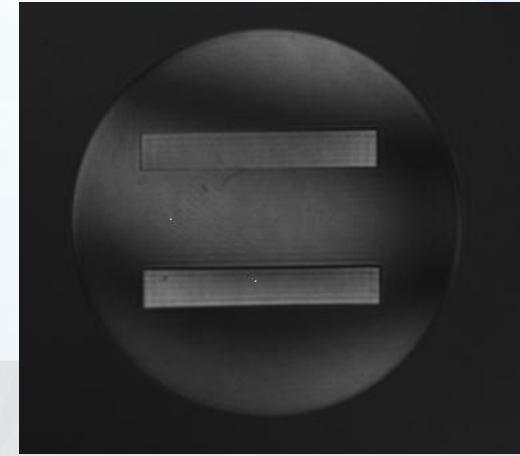
- Favorable electrical conductivity
- Optical transparency

Transparent conducting film in

- ✓ display
- ✓ organic light-emitting diode (OLED)
- ✓ solar cell



Raw interferogram



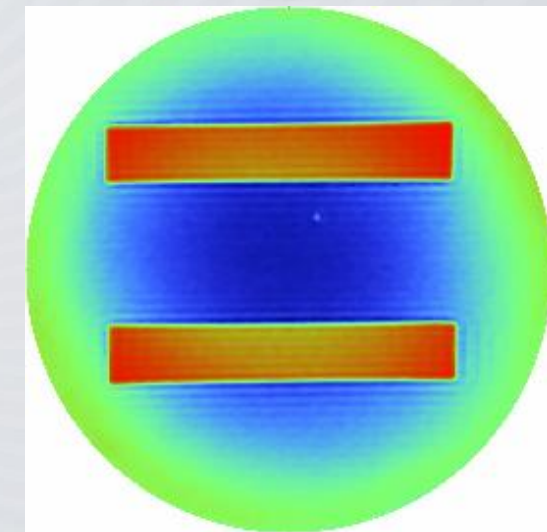
$$E_r = Er_0 \exp(i\theta)$$

$$E_1 = Er_1 t_0^2 \exp[i(\theta + \varphi)]$$

$$E_2 = Er_2 t_0^2 t_1^2 \exp[i(\theta + \varphi - \Delta)]$$

- Phase error  $\psi$  from phase difference  $\Delta$

$$\psi = \arctan \frac{B \sin \Delta}{A + B \cos \Delta}$$

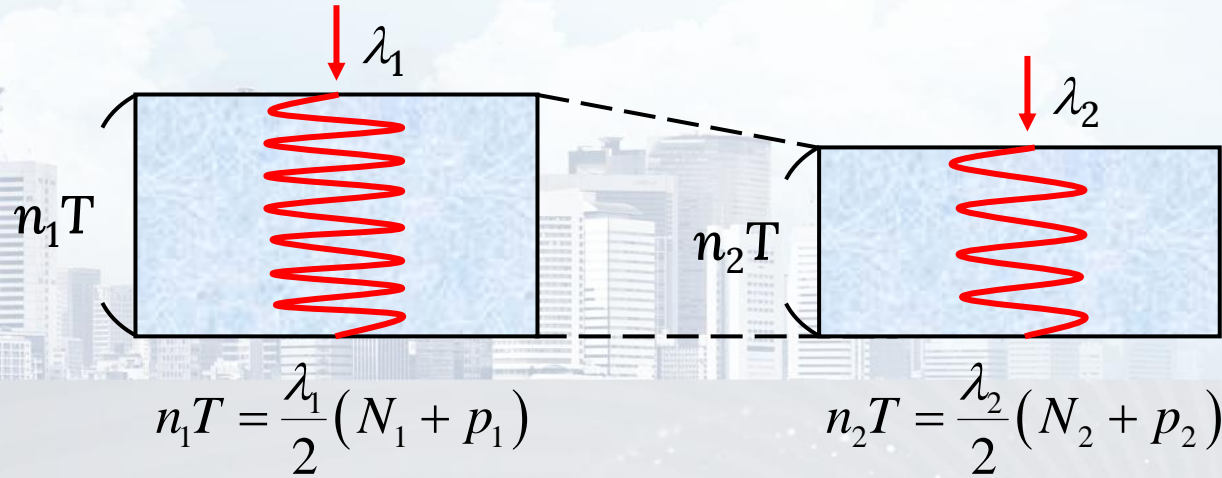


248.014 nm

0

# Application 4 : Absolute Thickness Profiling

- Wavelength tuning from  $\lambda_1$  to  $\lambda_2$



Absolute optical thickness at central wavelength  $\lambda_c [= (\lambda_1 + \lambda_2)/2]$

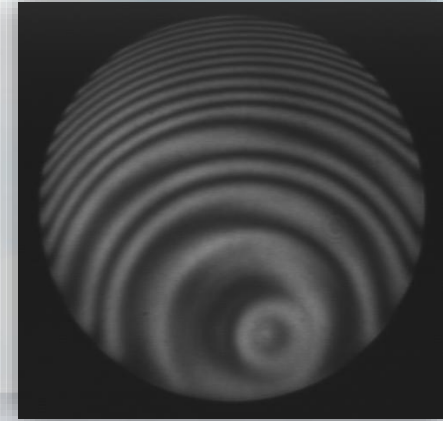
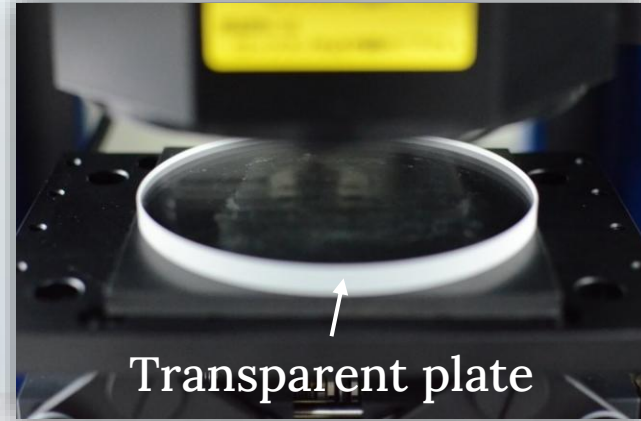
$$(n_g T)_{meas} = \frac{\lambda_s}{2} (N_1 - N_2 + p_1 - p_2)$$

Group refractive index:  $n_g = n \left( 1 - \frac{\lambda}{n} \frac{dn}{d\lambda} \right)$

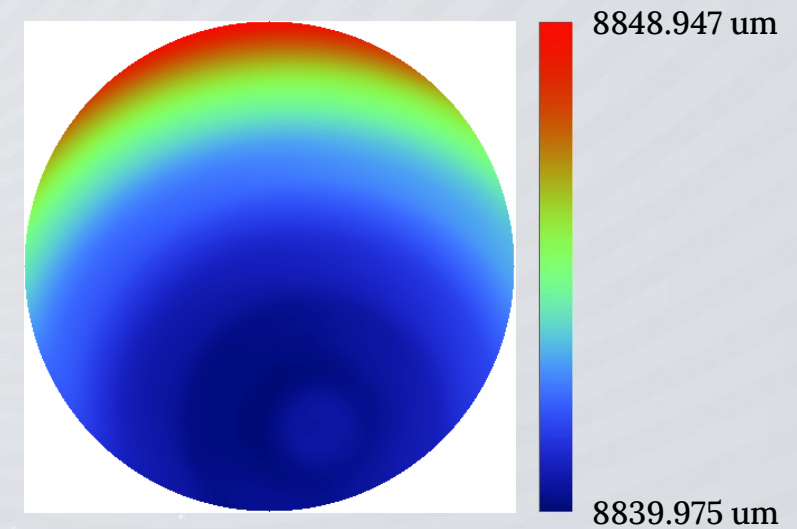
Synthetic wavelength:  $\lambda_s = \frac{\lambda_1 \lambda_2}{\lambda_2 - \lambda_1}$

Number of intensity variation  
: DFT analysis

Phase at initial and final wavelength  
: fringe analysis using wavelength tuning  
and  $4N - 1$  algorithm

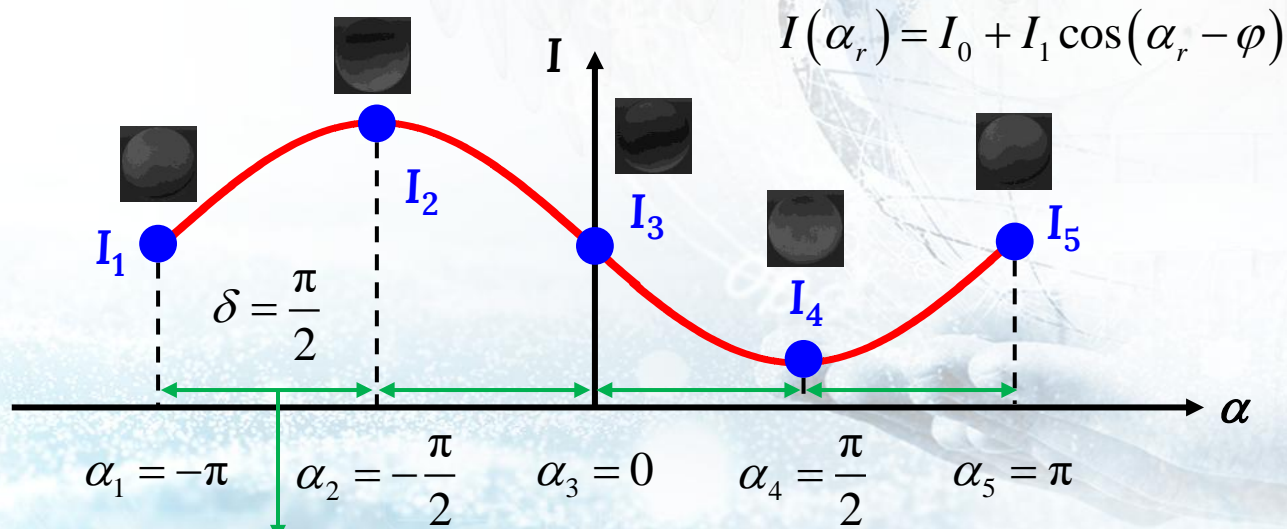


Final absolute optical thickness at  $\lambda_1$



# Background of Phase – Iterative Method

- Shortcomings of phase-shifting technique
  - Exactly same phase interval  $\delta$
  - Necessity of many frames for error compensation



Exactly same phase interval  $\delta$

Unrealistic!

- Simultaneous calculation of
  - Phase interval  $\delta(\alpha_r)$
  - Target phase  $\varphi$

Phase-iterative method



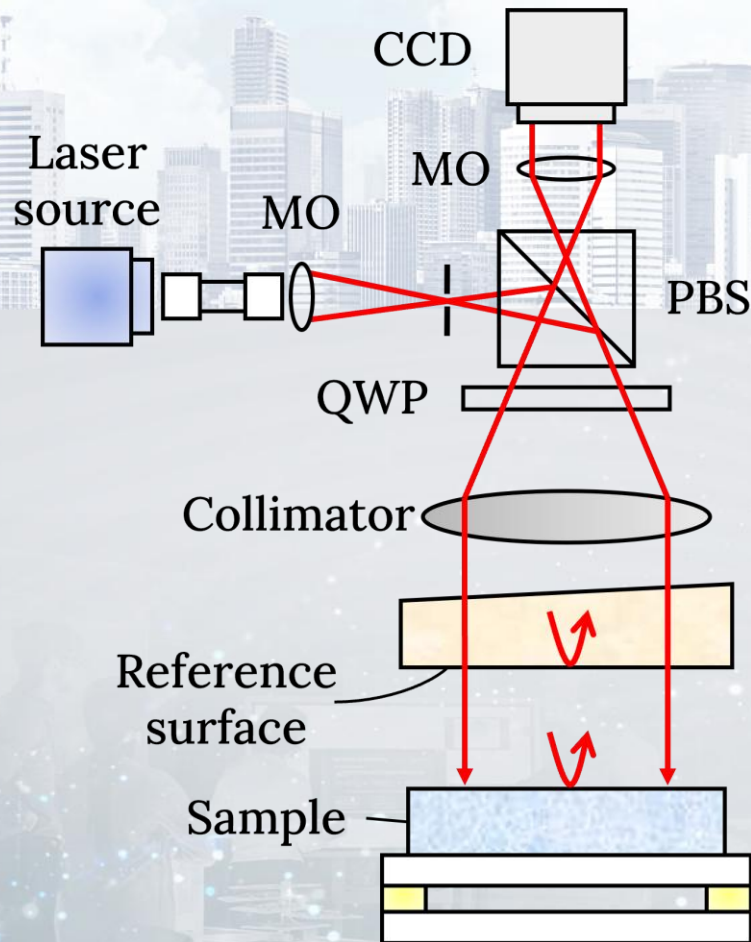
Compensation ability for 2<sup>nd</sup> harmonics



Harmonic phase-iterative method

# Application : Surface Topography of Wafer

- Larger-aperture Fizeau interferometer

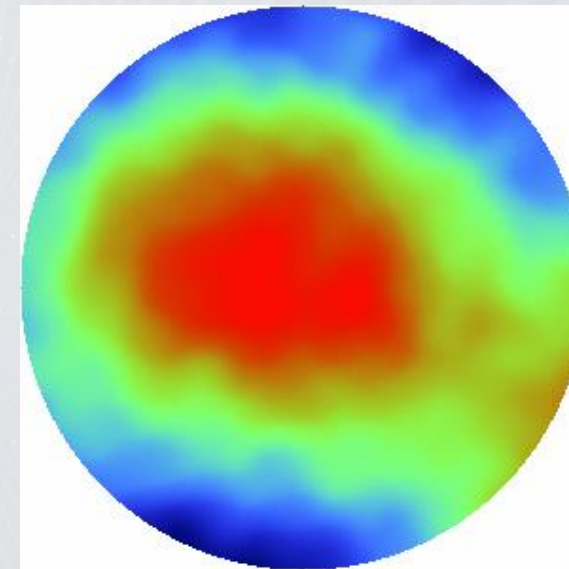
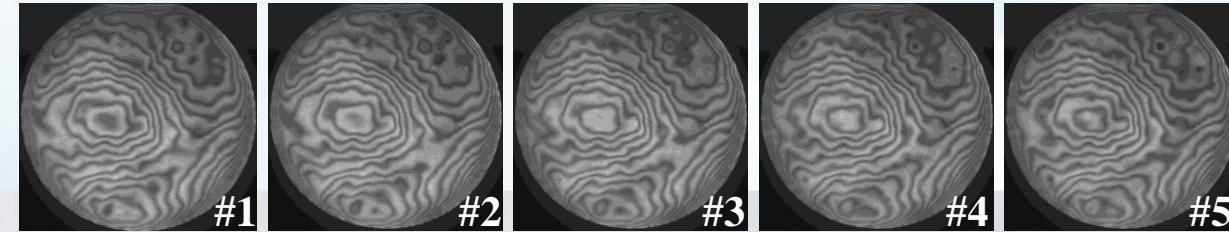


Reflectivity: 30%



- Surface profiling of silicon wafer

- Surface of the four-inch silicon wafer was obtained by using the harmonic phase-iterative analysis and five-frame interferograms.



343.5517 nm

0

Repeatability  
uncertainty: 3.5 nm

# Phase Extraction using Deep Learning

## ■ Benefits of using deep learning

- No systematic errors
- Less than three interferograms
- Fringe patterns with random phase shifts

## ■ Train data

- One phase and fringe patterns are composed a train dataset
- Simulation dataset (Not real data)

## ■ Train model

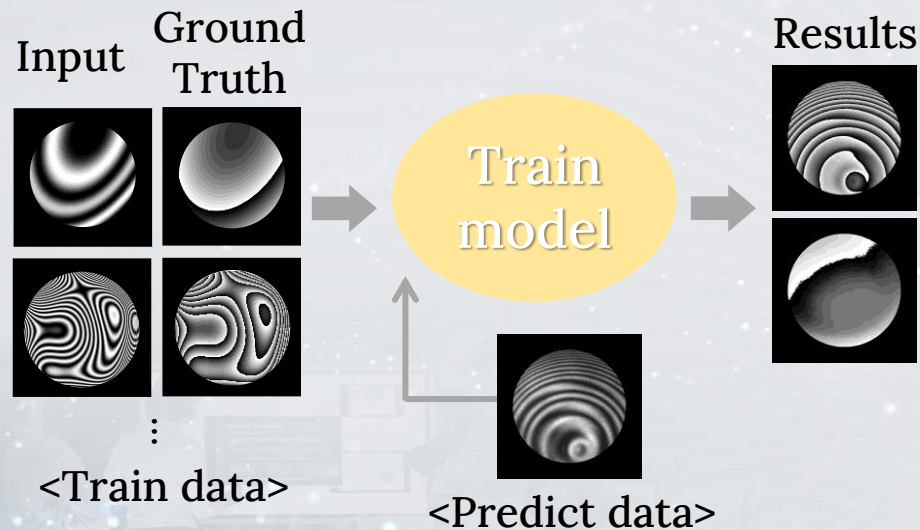
- Network, Layers, loss function, optimizer, and hyperparameters are determined

## ■ Predict data

- The predict data (real fringe patterns) is given to the trained model

## ■ Results

- The result phase corresponding to the predict data (interferograms) can be obtained.



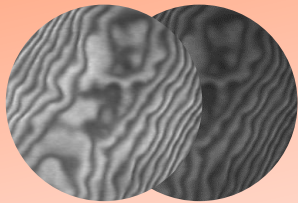
► Deep learning phase extraction

# Fringe Analysis using Deep Learning

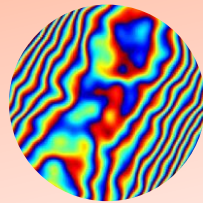
On-going projects about fringe analysis using deep learning

1

2-frame  
Phase  
extraction

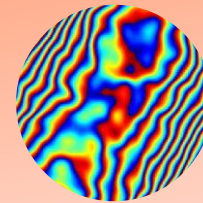


Neural  
Network

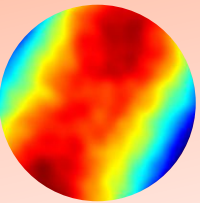


2

Phase  
unwrapping

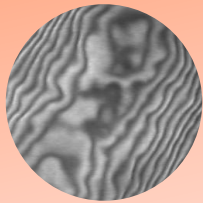


Neural  
Network

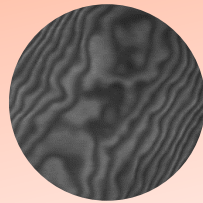


3

Fringe  
duplication

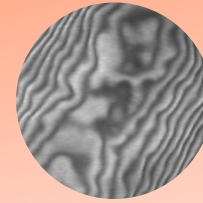


Neural  
Network

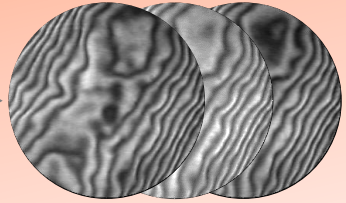


4

Fringe  
duplication  
for PST

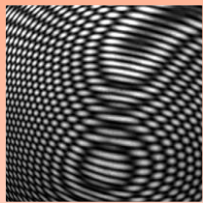


Neural  
Network

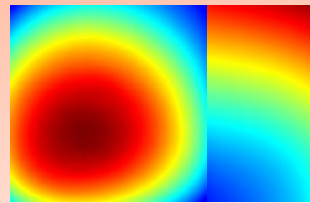


5

Simultaneous  
profiling

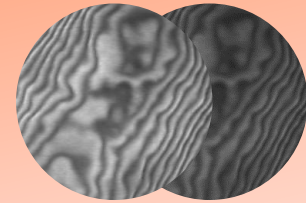


Neural  
Network

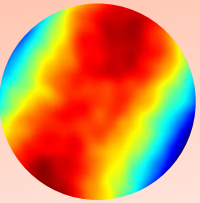


6

Absolute  
profiling



Neural  
Network





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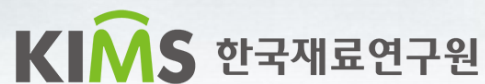


AMOI  
Advanced Manufacturing & Optical Instrumentation Lab

# Machine Tools



東京大学  
THE UNIVERSITY OF TOKYO



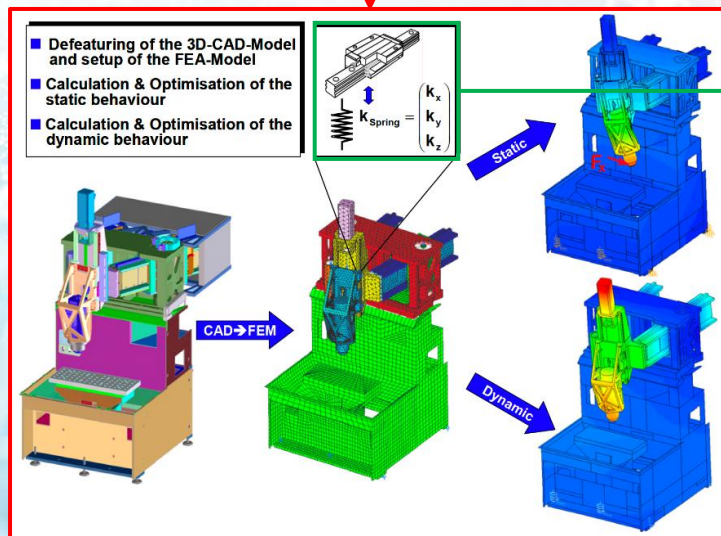
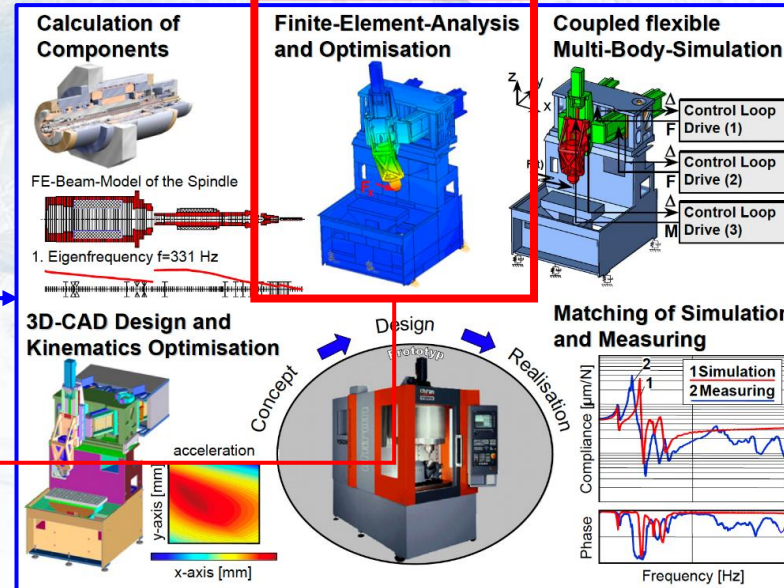
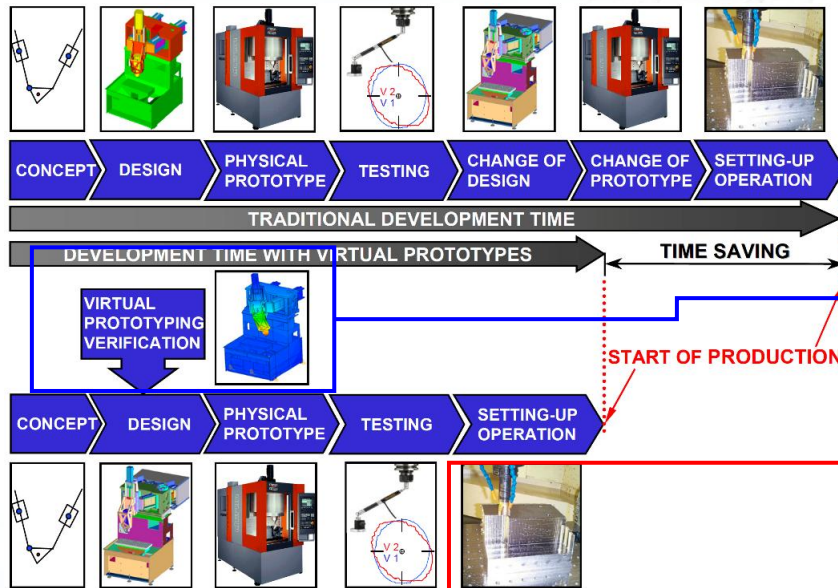
한국재료연구원



한국기계연구원  
KOREA INSTITUTE OF MACHINERY & MATERIALS



# Virtual Machine Tools



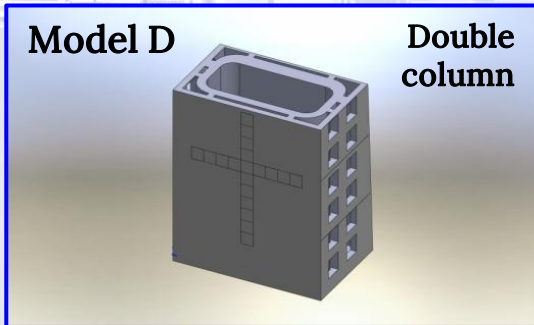
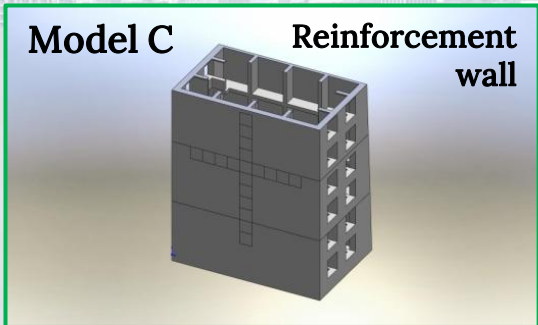
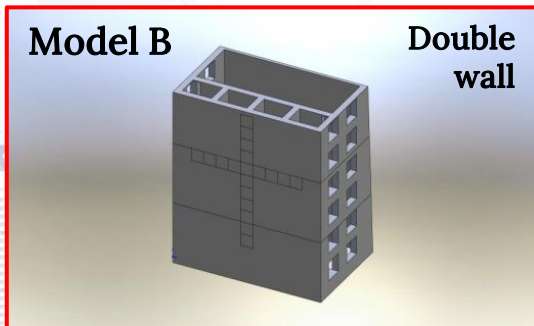
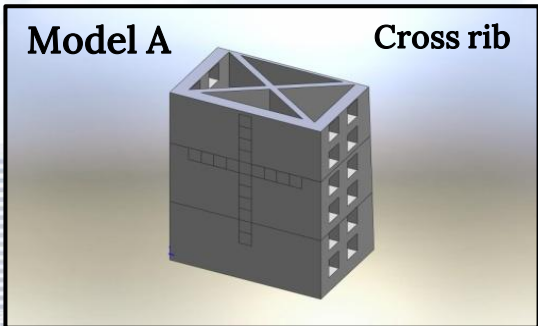
- Analysis types of FE analysis
  - Linear static
  - Nonlinear static
  - Dynamic
  - Thermal

Modeling of machine tool joints

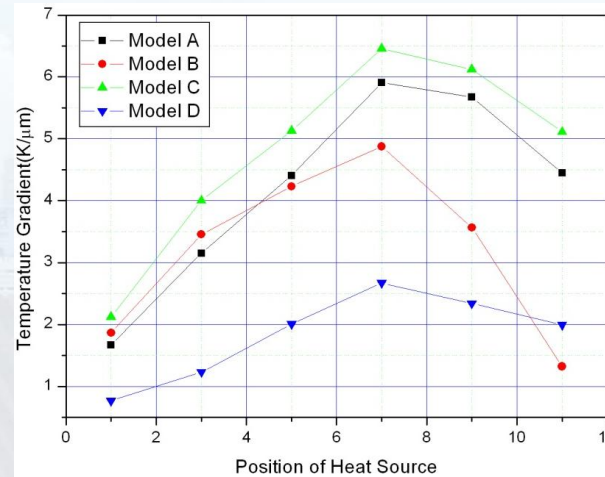
Y. Altintas, C. Brecher, M. Weck, and S. Witt, "Virtual machine tool," CIRP Annals 54(2), 115-138 (2005).

# Thermal Properties of Column by Rib Structure

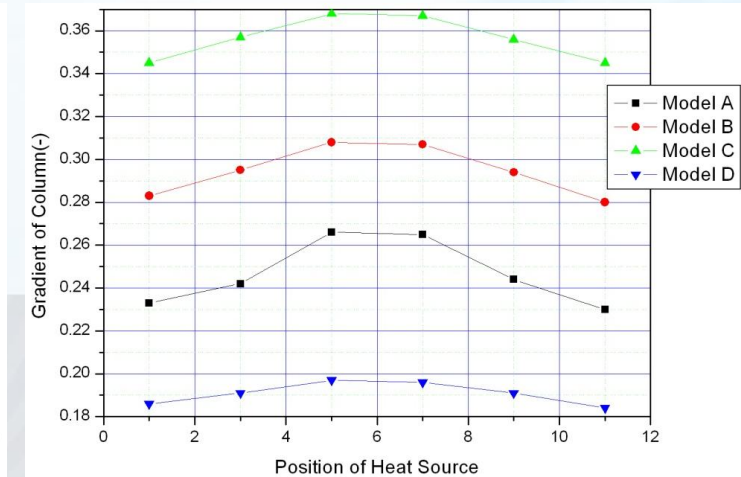
- Column rib model



- Temperature gradient



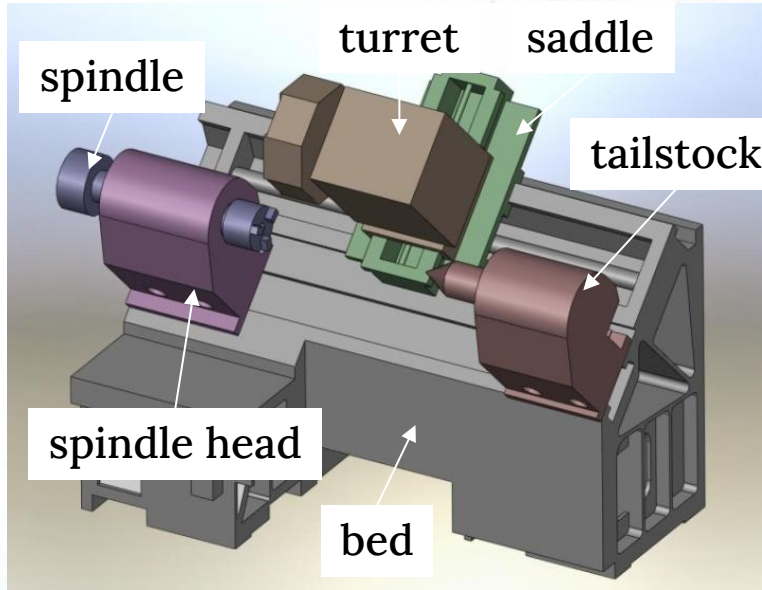
- Deflection gradient



- Model D (double column model) shows the best thermal performance from the aspect of temperature gradient and deflection of column
- Model C (reinforcement wall model) does not have the good thermal properties because the deflection of column is too large

# Structural Analysis of Turning Center

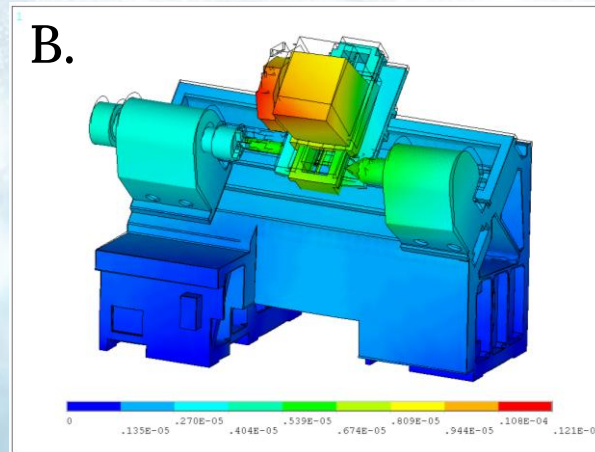
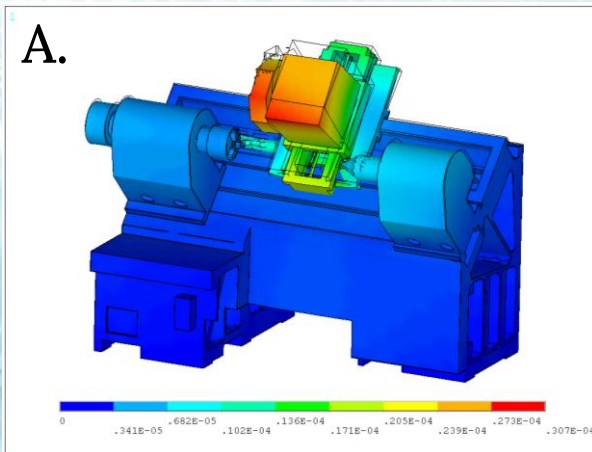
- Suppression of static deflection of turret of hard tuning center using CFRP



	Density [kg/m <sup>3</sup> ]	Young's modulus [GPa]	Poisson ratio
GC300	7,300	90.0	0.25
USN150	1,550	$E_1 = 130.0, E_2 = 10.0, G_{12} = 5.06$	0.28

A. GC300

B. turret (USN150), others (GC300)



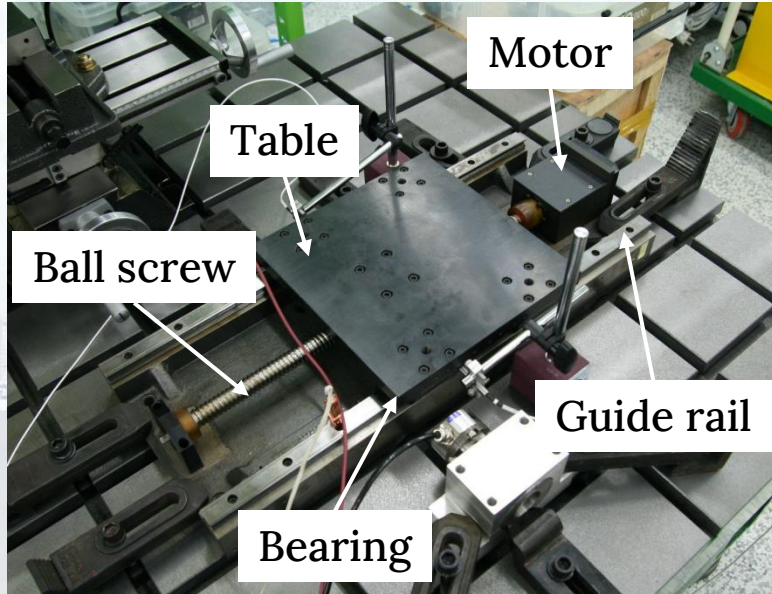
A. Max. deflection

: **30.7 um**

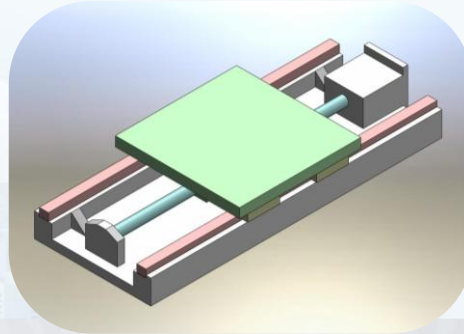
B. Max. deflection

: **12.1 um**

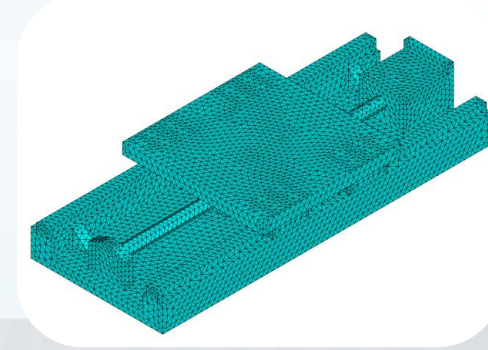
# Modeling of Machine Tool Joint – Feed Drive



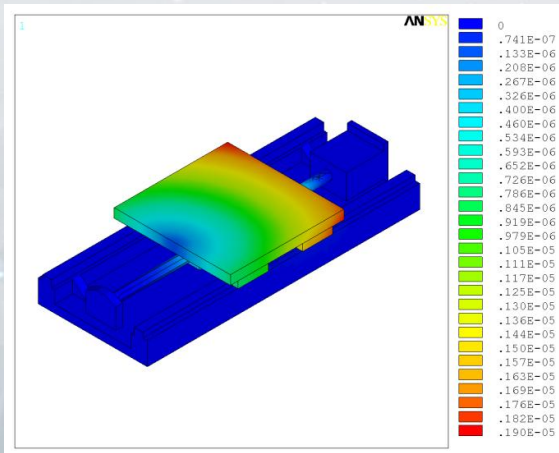
- 3D CAD modeling



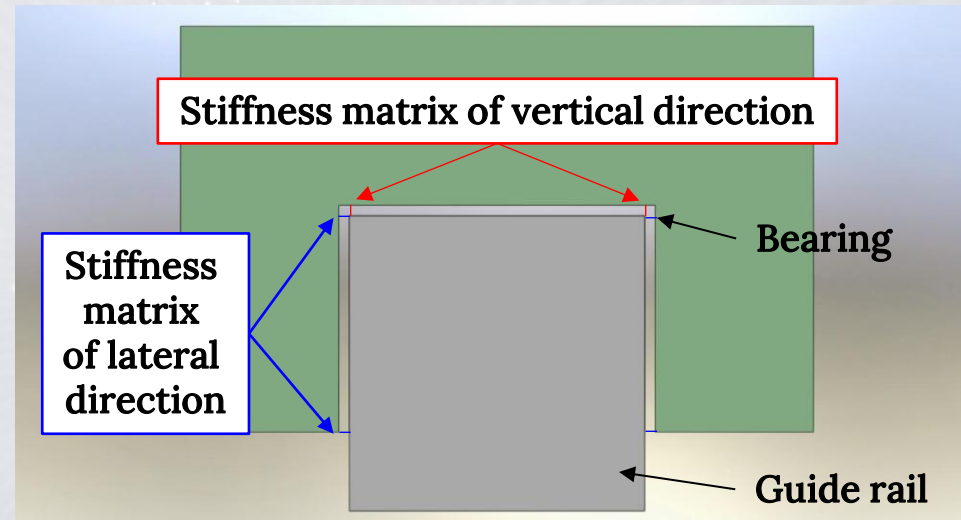
- FEA modeling



- FEA analysis

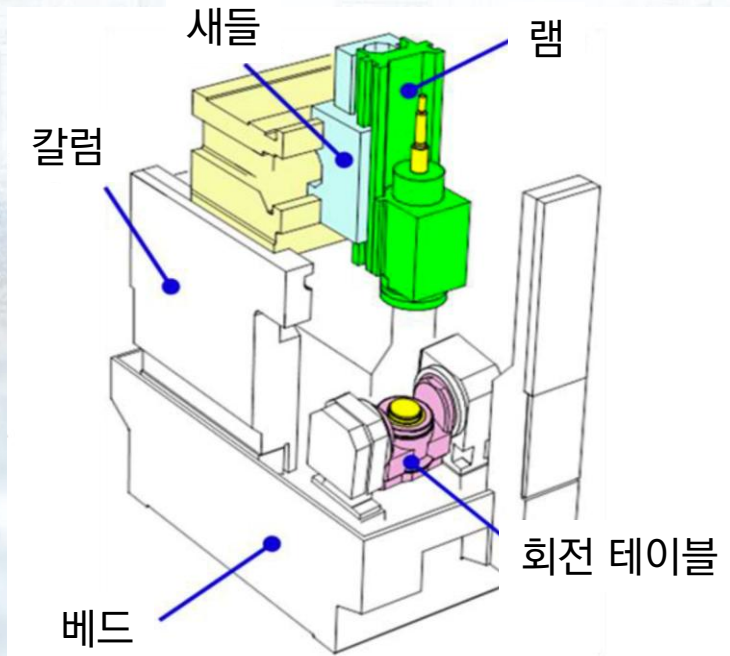










- Stiffness matrix



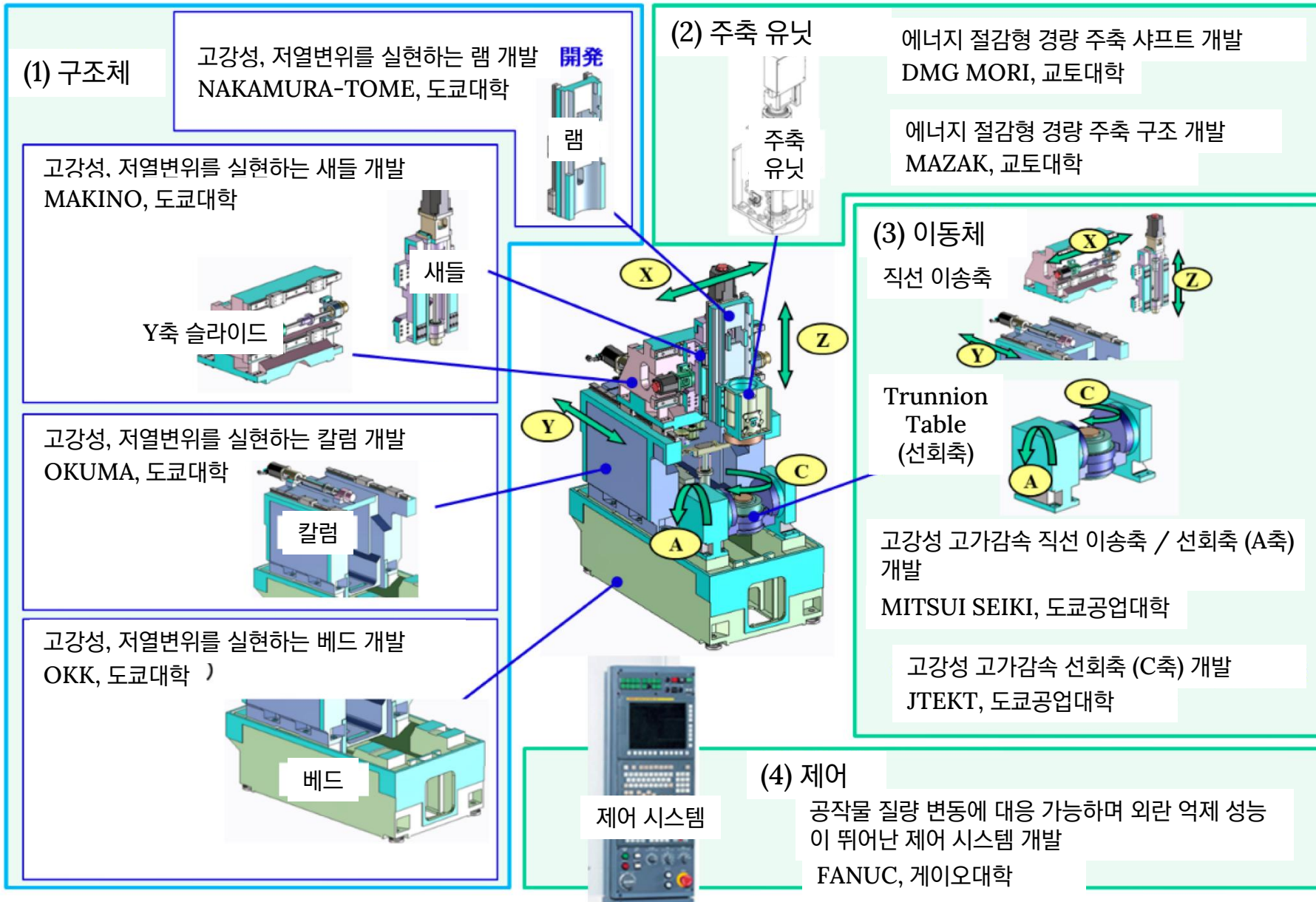
# CFRP Machine Tools

- 기술개발책임자: A. Ieki (OKUMA)
- 대표실행책임자: H. Senda (OKUMA), N. Sugita (The University of Tokyo)



<p>구조체 (칼럼, 베드, 새들, 램)</p>		
<p>주축 및 주축 구동부</p>		
<p>직선 이송 시스템 및 회전 테이블</p>		
<p>제어 시스템</p>		

# CFRP Machine Tools



# CFRP Machine Tools

**램:**  
CFRP in steel square pipe

**새들:**  
CFRP + Aluminum alloy

**이송축:**  
CFRP in steel pipe

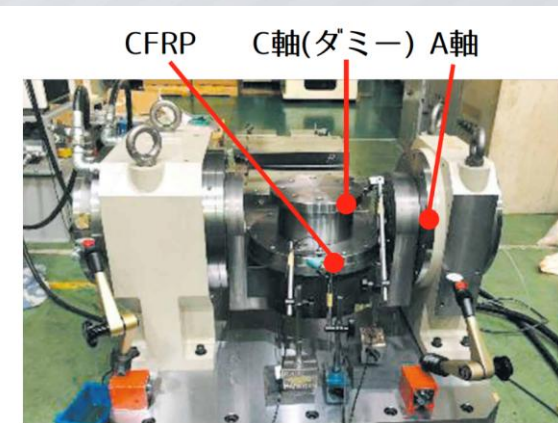
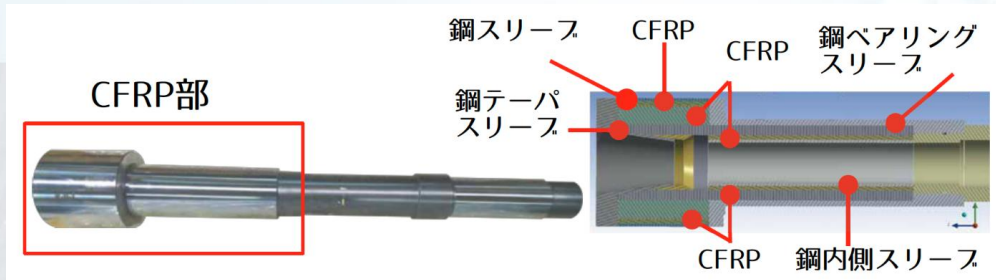
**칼럼:**  
CFRP & REC in gray cast iron

**베드:**  
CFRP & REC in gray cast iron



**주축:**  
CFRP in steel pipe

**Trunnion table:**  
A-axis: CFRP and cast iron with steel sleeve  
C-axis: CFRP in steel pipe



# Development of Steel Composite

- 비철기지 금속복합소재 제조에 사용하던 용융가압함침공정의 개념을 응용하여 철강기지 금속복합소재 개발을 시도하여 이 분야 새로운 장을 개척 (용해온도 1,000 °C → 1600 °C)
  - 용융가압함침공정 개념설계/장치제작/최적제조공정/특성제어 등



[ 독자기술 용융가압함침 공정 장비 ]

[ 우수한 물성: 경량, 고강도, 저열팽창, 고내마모 ]

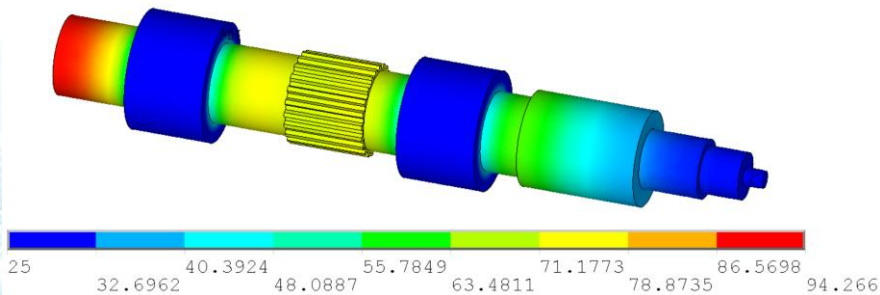
## <응용 연구를 통하여 확보한 기술>

- TiC<sub>p</sub>/Steel(금형강(SKD61), 공구강(SKH51), 저탄소강(S20C), 스테인레스강(SUS431))
- 강화재 형상 및 강화재 체적을 제어
- 계면구조(TEM) 및 미세조직 형성기구 규명 (Ostwald ripening (core-rim 구조))
- 조성/계면/분산 제어를 통한 우수한 물성 확보 및 신뢰성 향상(데이터베이스)
- 대형시제 제조 (Φ200, 35t / 200 mm 급) 및 응용분야 맞춤 물성 제어
- 응용물성 해석: 스피들 적용시 우수한 열적(저열변형)/동적(진동) 특성

# Thermal Analysis of Steel Composite Spindle

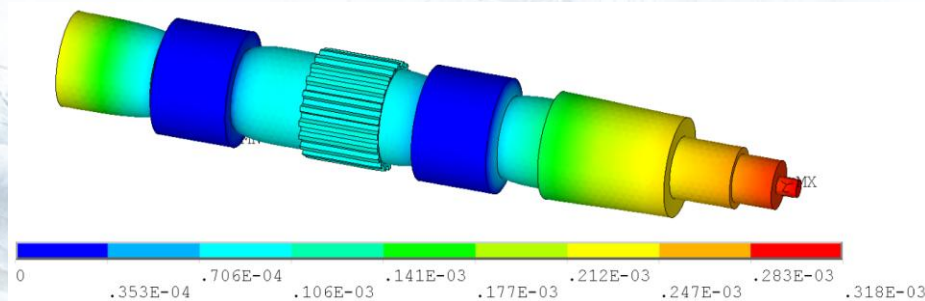
	Specific heat [J/kg·K]	Density [g/cm <sup>3</sup> ]	Young's modulus [GPa]	Poisson ratio	Thermal conductivity [W/m·K]	Coefficient of thermal expansion [10 <sup>-6</sup> /K]
TiC-SUS431 (KIMS)	551	6.12	<b>240</b>	0.28	<b>15.1</b>	<b>8.74</b>
SUS431	480	7.76	200	0.30	21.3	10.09
GC300	565	7.30	90	0.25	55.8	17.10

## Temperature distribution



	Maximum Temperature [°C]
TiC-SUS431	94.2
SUS431	102.9
GC300	104.1

## Thermal deflection



	Thermal deflection [μm]
TiC-SUS431	318
SUS431	379
GC300	848

# KEIT Project (산업통상자원부 소재부품개발사업)

- 과제명 : 가공 성능 최적화 및 사용편의성 향상을 위한 스마트 공작기계용 지능화 요소 기술 개발  
부산대 과제명: 민감도 분석법과 보정 알고리즘을 이용한 5축 공작기계 Kinematic Error 보정 시스템 개발
- 연구개발 목표
  - ❖ 차세대 다축 복합 스마트 머신의 가공 정밀도와 생산성을 향상시킬 수 있는 지능화 요소기술 개발
  - ❖ 개발된 요소기술의 개방형 운영체제 탑재 및 실증
- 수행기간 : 2023. 07. 01 ~ 2026. 12. 31. 총 42개월
- 연구 컨소시엄 구성
  - ❖ 주관기관 : 한국기계연구원 (책임자 : 노승국 책임연구원)
  - ❖ 공동연구개발기관 : (주)DN솔루션즈 (책임자 : 이창호 책임매니저)
  - ❖ 공동연구개발기관 : 연세대학교 산학협력단 (책임자 : 윤준영 교수)
  - ❖ 공동연구개발기관 : 부산대학교 산학협력단 (책임자 : 김양진 교수)
  - ❖ 공동연구개발기관 : 경희대학교 산학협력단 (책임자 : 엄주명 교수)

# KEIT Project (산업통상자원부 소재부품개발사업)

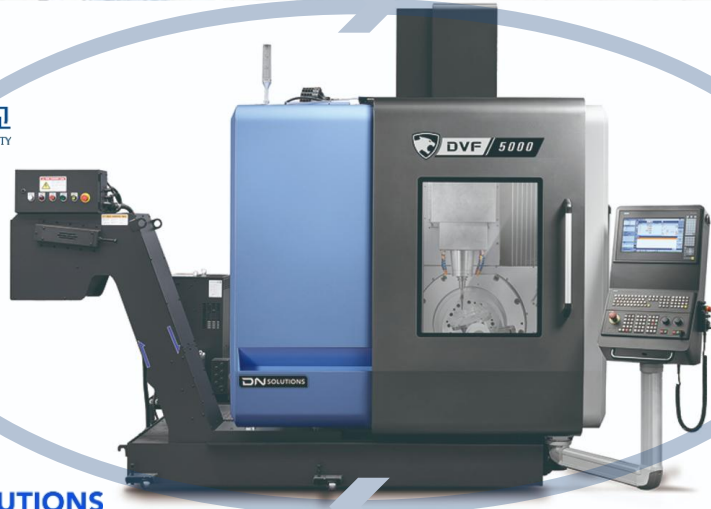
- Smart Machine 의 핵심 지능화 기술:  
AI, IoT, DX등의 최신 기술을 융합하여 장비의 상태를 스스로 인지/판단하여 높은 생산성과 효율성 실현

## C 보정 (Compensation)

- 절삭부하감지기능
- 열변위보정 기술
- 5축 기하오차 측정/보정 기능
- 밀턴 테이블 불평형 검출 기술
- 능동형 진동 저감 기술



## 다축 복합 스마트 가공기



## P 예측/알림 (Predictive/alerts)

- 비전 센서 기반 공구 파손 검출 기능
- 부품 교체 주기 자동 알림 기능
- 장비 상태 모니터링/예지보전 기술
- 충돌방지 기술
- 스펀들 상태 진단 기술



본과제 개발 영역 - 우선순위 및 개발 일정 고려하여 선정

## O 최적화 (Optimization)

- 비접촉식 조도 측정기를 통한 가공 조도 및 품위 측정 기술
- 가공 조건 최적화 기술 (오프라인)
- 자동 공정 스케줄링 기능
- 생산성 향상을 위한 프로그래밍 최적화 기술
- Smart CBS 기능



## U UX (User-eXperience)

- 자동 공구 정보 인식 기능 (Tool-ID)
- 가공 조건 실시간 편집 및 저장 기능
- 실시간 칩 처리 기능 / 대화형 장비 (운전/유지보수)
- NC 중립 HMI H/W & S/W 플랫폼
- 음성 인식 기술 / 모바일 원격 제어 기능
- 긴급 호출 기능 / 자동 전원 및 워밍업 제어 기능

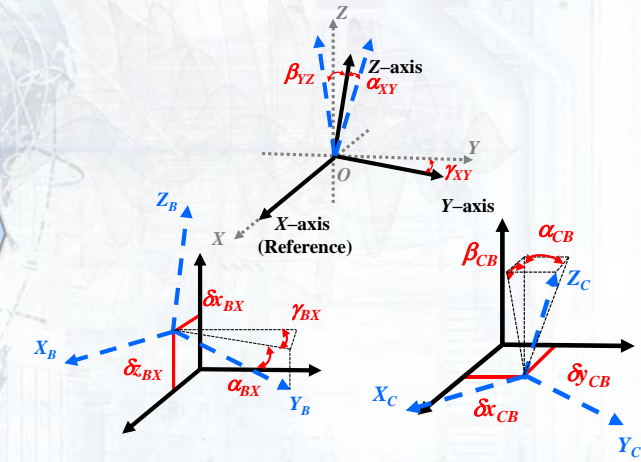
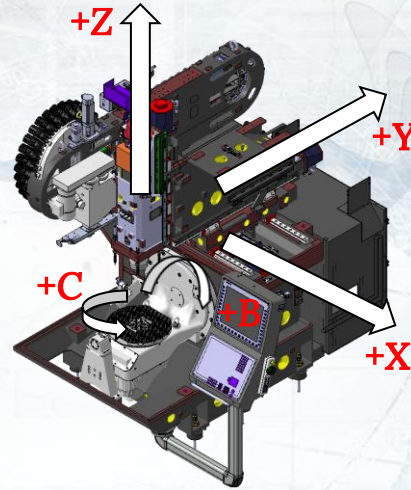


# 5축 공작기계 오차 보정

- 5-Axis machine tool

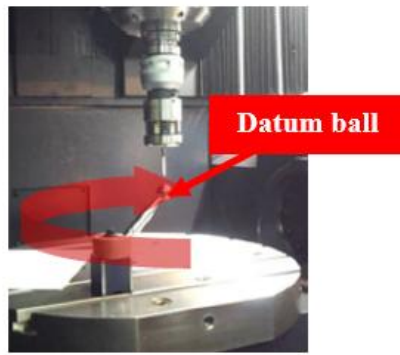


- Kinematic error modeling



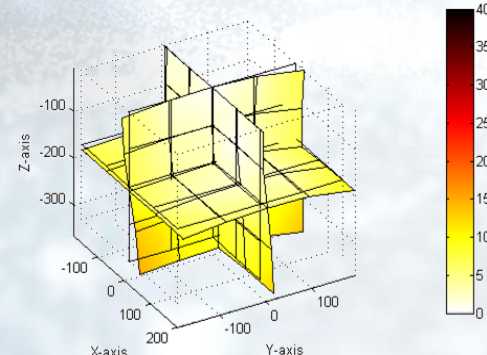
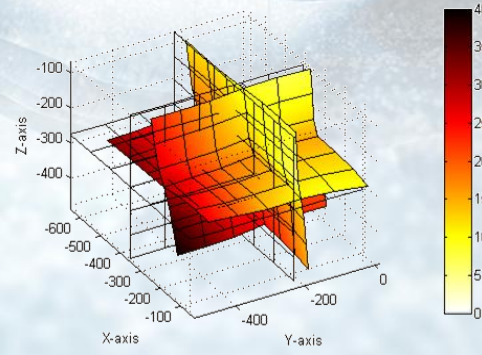
Kinematic error

- Identification of kinematic error



Measurement cycle

- Compensation of volumetric error



Before compensation

After compensation



**부산대학교**  
PUSAN NATIONAL UNIVERSITY



**AMOI**  
Advanced Manufacturing & Optical Instrumentation Lab

# Advanced Manufacturing & Optical Instrumentation Lab.

## 첨단생산 및 광계측 실험실

---

Pusan National University  
School of Mechanical Engineering  
Prof. Yangjin Kim

# Lab Alumni (Mar. 2025)



Miss Jiwon Seo

FEB 2022  
SK on



Dr. Wonjun Bae

FEB 2023  
DN Solutions

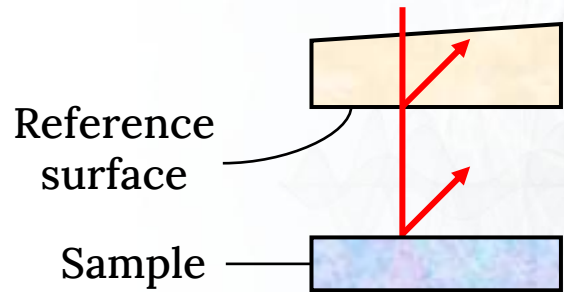


Dr. Sungtae Kim

FEB 2024  
DN Solutions

# Conventional Phase – Shifting Technique

- Simple two-layer Fizeau interferometer



- Phase-shifting algorithm

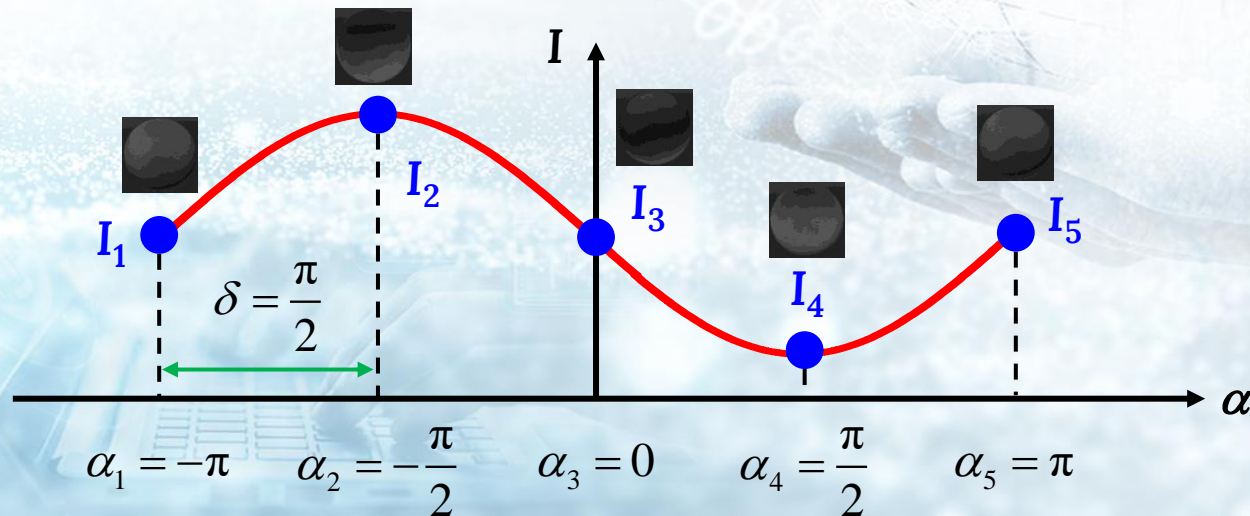
$$\varphi = \arctan \frac{\sum_{r=1}^M b_r I(\alpha_r)}{\sum_{r=1}^M a_r I(\alpha_r)}$$

$r$ : sampling number

$a_r, b_r$ : sampling amplitudes

$M$ : image number for phase calculation

- During wavelength tuning  $I(\alpha_r) = I_0 + I_1 \cos(\alpha_r - \varphi)$



- Error sources

- ✓ Harmonic components
- ✓ Phase-shift error
- ✓ Coupling error  
(between harmonics and phase-shift error)
- ✓ Nonlinear error  
(vibration, temperature fluctuation)

# Design Methods of Phase – Shifting Algorithm

## **Linear equation theory** (proposed by K. Hibino)

- ◆ Group of linear equations for the elimination of phase-shift errors
- ◆ 9-frame, 13-frame, etc.

## **Characteristic polynomial theory** (proposed by Y. Surrel)

- ◆ Flexible design method using polynomial of algorithm
- ◆ Applicable to simultaneous measurement of surface shape and thickness
- ◆ 17-frame, 13-frame, 19-frame, 15-frame, etc.
- ◆  $3N - 2$ ,  $4N - 3$ ,  $5N - 4$ ,  $6N - 5$ ,  $7N - 6$ , etc.
- ◆  $4N - 1$ ,  $5N - 2$ ,  $6N - 3$ , etc.

## **Extended averaging method** (proposed by K. Creath)

## **Fourier description method** (proposed by K. Freischlad and C. L. Koliopoulos)

$$\varphi = \arctan \frac{\sum_{r=1}^M b_r I(\alpha_r)}{\sum_{r=1}^M a_r I(\alpha_r)}$$

$a_r, b_r$ : sampling amplitudes  
M: image number